



11-08-2002

TI-31816

FORM PTO-1595

RE

102276136
PATENT ONLYU.S. Department of Commerce
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Makoto Yoshino, 10/01/2002
Kunio Sakamoto, 10/01/2002
Kensho Murata, 10/01/2002

Texas Instruments Japan Ltd., 10/08/2002

Additional name(s) & address(es)
Attached? ☐ Yes ☒ No

2. Name and Address of receiving party(ies):

Name: Texas Instruments Incorporated
Address: P. O. Box 655474, M.S. 3999
City: Dallas
State: Texas Zip: 75265Additional name(s) & address(es)
attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ OtherExecution Date: October 1, 2002, and October 8, 2002.

4. Application number(s) or patent number(s).

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

10/226,539Additional numbers attached? ☐ Yes ☒ NoAdditional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MICHAEL K. SKREHOT
Address: Texas Instruments Incorporated
P. O. Box 655474, M.S. 3999
City: Dallas
State: Texas Zip: 752656. Number of applications and patents involved: 17. Amount of fee enclosed or authorized to be charged: \$40.008. Texas Instruments Incorporated, Deposit Account No.: 20-0668

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
SignatureMICHAEL K. SKREHOT, REG. NO.: 36,682
Name of Person Signing10-21-02
DateTotal number of pages including cover sheet, attachments and document: 411/08/2002 BTOM11 00000013 200668 10226539
01 FC:8021 40.00 CHPATENT
REEL: 013457 FRAME: 0835

ASSIGNMENT

WHEREAS, TEXAS INSTRUMENTS JAPAN, LTD. (hereinafter **TIJ**), a Japanese company having its headquarters at 24-1 Nishi-Shinjuku 6-chome, Shinjuku-ku, Tokyo, Japan, under the laws of Japan made application, in its own name, for Letters Patent in Japan in respect of an invention as set forth below;

WHEREAS, the or each below named inventor (hereinafter **INVENTOR**) is the or an inventor of the said invention;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, having a place of business at 7839 Churchill Way, Mail Station 3999, Dallas, Texas 75251, USA, is desirous of acquiring the entire right, title and interest in and to the said invention outside of Japan, and in and to the U.S. patent application as identified hereinafter and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, **TIJ** and **INVENTOR** sell and assign to the said **TEXAS INSTRUMENTS INCORPORATED**, its successors and assigns the entire right, title and interest in and to the said invention in the U.S.A. and all other countries outside Japan; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and the right to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

TIJ and **INVENTOR** hereby authorize and request the Commissioner of Patents to issue U.S. patents for said invention, or U.S. patents resulting therefrom, insofar as the interest of **TIJ** and **INVENTOR** is concerned to the said **TEXAS INSTRUMENTS INCORPORATED**, as assignee of the entire right, title and interest.

TIJ and **INVENTOR** further agree to communicate to **TEXAS INSTRUMENTS INCORPORATED** or to its successors, assigns and legal representatives, any facts known to **TIJ** and **INVENTOR** respecting the said invention, and at the expense of **TEXAS INSTRUMENTS INCORPORATED**, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally do everything possible to aid said **TEXAS INSTRUMENTS INCORPORATED**, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside of Japan.

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

Title of Invention

Japanese Serial No.: **13(2001)-252658** Filed: **23 August 2001**

U.S. Application Serial No.: **10/226,539** Filed: **23 August 2002**

IN WITNESS WHEREOF, this Agreement has been executed as set forth below;

Signed at Tokyo, Japan on October 8, 2002

by **Texas Instruments Japan, Ltd.**

Name Kb. for Balu

Krishnan Balasubramanian

Title Representative Director and President

Date 10/08/02

and by the **INVENTORS:**

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Date